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JP 5-102343

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DIALOG(R)File 347:JAPIO  
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04110643  
MOUNTING STRUCTURE OF SEMICONDUCTOR DEVICE AND MOUNTING METHOD OF  
SEMICONDUCTOR DEVICE

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(ELECTRONICS -- Electronic Components)  
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#### ABSTRACT

PURPOSE: To provide a method by which the reliability on the connection is high and which never causes electric conductivity trouble, in case of mounting a semiconductor element on a glass board, with the active face opposite to it.

CONSTITUTION: A semiconductor element 1 is loaded on a wiring board 4 where a through hole 9 is opened, and the adhesive for fixing is hardened by heat. Moreover, in case of having used a photosetting adhesive, it can be made the hardening from the rear of the semiconductor device and the hardening from the rear of the glass board. This way, by having opened a through hole, the adhesive can be escaped to outside, so it does not give stress to the connection. Moreover, even if trouble should be found, the semiconductor device could be removed simply from the glass wiring board.

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DIALOG(R)File 351:DERWENT WPI

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Structure to mount semiconductor element on glass wiring substrate - with  
removable optical hardening adhesive around semiconductor element for  
replacing element when connection is faulty NoAbstract

Patent Assignee: SEIKO EPSON CORP (SHIH )

Number of Countries: 001 Number of Patents: 001

Patent Family:

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